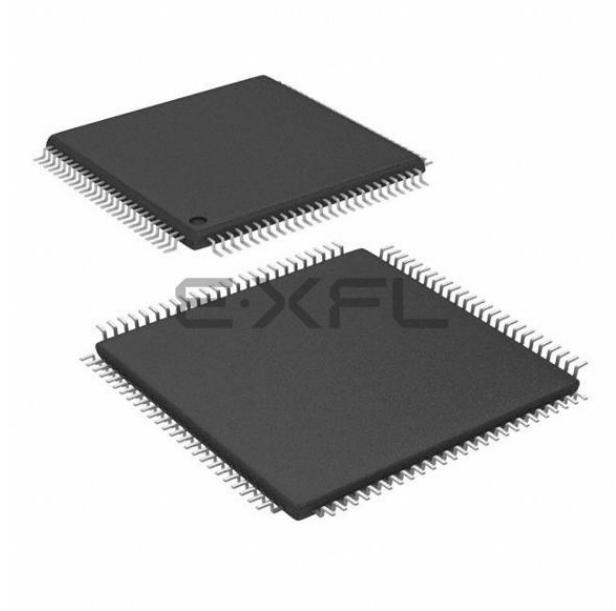

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	81
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx450f128l-i-pf

TABLE 4: PIN NAMES FOR 100-PIN DEVICES (CONTINUED)

100-PIN TQFP (TOP VIEW)(1,2,3)

PIC32MX330F064L
PIC32MX350F128L
PIC32MX350F256L
PIC32MX370F512L

Pin #	Full Pin Name	Pin #	Full Pin Name
71	RPD11/PMCS1/RD11	86	VDD
72	RPD0/RD0	87	RPF0/PMD11/RF0
73	SOSCI/RPC13/RC13	88	RPF1/PMD10/RF1
74	SOSCO/RPC14/T1CK/RC14	89	RPG1/PMD9/RG1
75	VSS	90	RPG0/PMD8/RG0
76	AN24/RPD1/RD1	91	TRCLK/RA6
77	AN25/RPD2/RD2	92	TRD3/CTED8/RA7
78	AN26/RPD3/RD3	93	PMD0/RE0
79	RPD12/PMD12/RD12	94	PMD1/RE1
80	PMD13/RD13	95	TRD2/RG14
81	RPD4/PMWR/RD4	96	TRD1/RG12
82	RPD5/PMRD/RD5	97	TRD0/RG13
83	PMD14/RD6	98	AN20/PMD2/RE2
84	PMD15/RD7	99	RPE3/CTPLS/PMD3/RE3
85	VCAP	100	AN21/PMD4/RE4

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx), with the exception of RF6, can be used as a change notification pin (CNAx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

3: RPF6 (pin 55) and RPF7 (pin 54) are only remappable for input functions.

NOTES:

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- *"Using MPLAB® ICD 3"* (poster) DS50001765
- *"MPLAB® ICD 3 Design Advisory"* DS50001764
- *"MPLAB® REAL ICE™ In-Circuit Debugger User's Guide"* DS50001616
- *"Using MPLAB® REAL ICE™ Emulator"* (poster) DS50001749

2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

2.7 Trace

The trace pins can be connected to a hardware trace-enabled programmer to provide a compressed real-time instruction trace. When used for trace, the TRD3, TRD2, TRD1, TRD0 and TRCLK pins should be dedicated for this use. The trace hardware requires a 22 Ohm series resistor between the trace pins and the trace connector.

2.8 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT

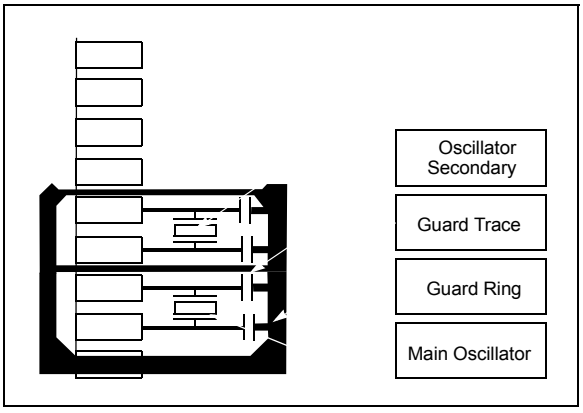
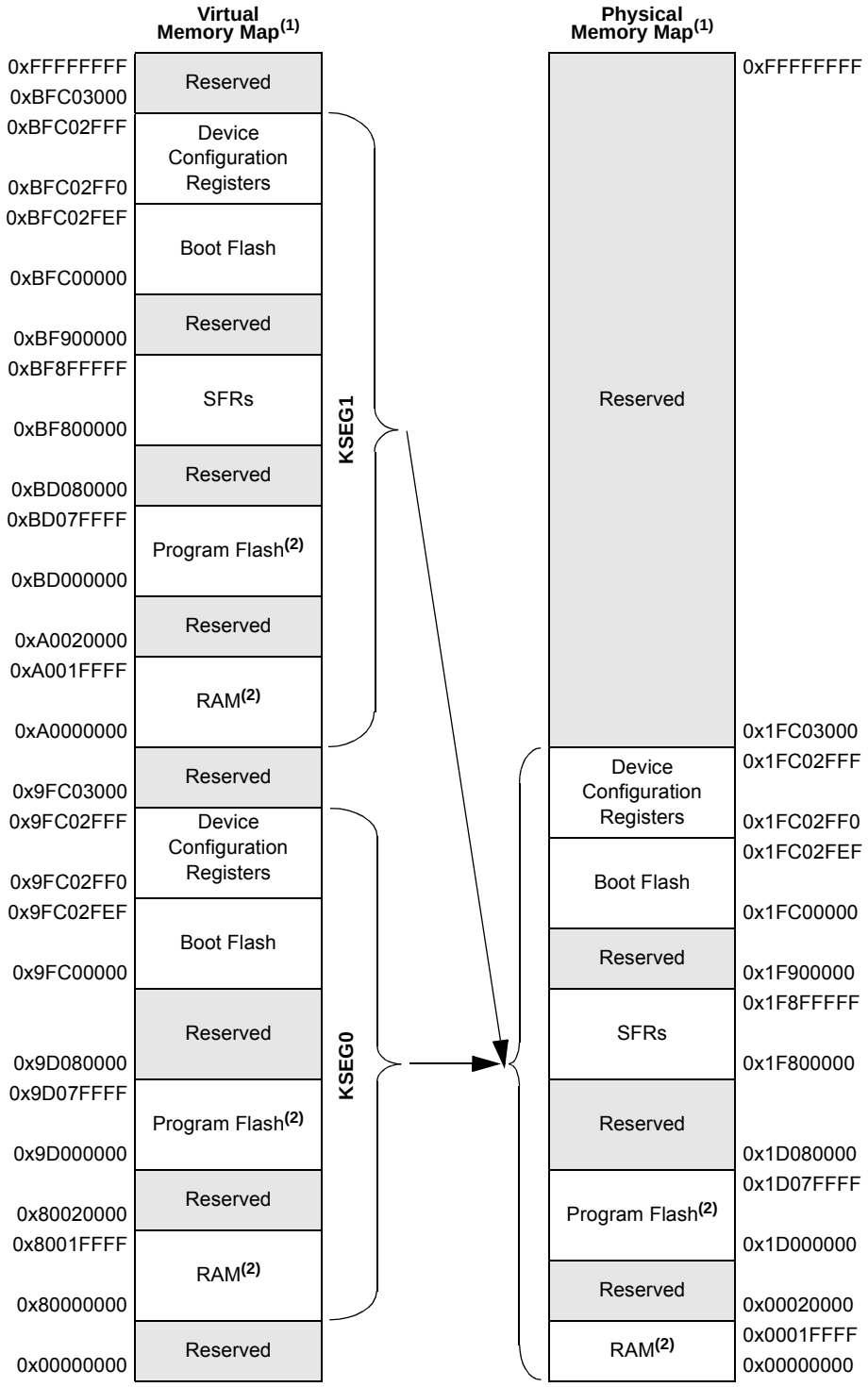


FIGURE 4-4: MEMORY MAP FOR DEVICES WITH 512 KB OF PROGRAM MEMORY



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

REGISTER 7-4: IFSx: INTERRUPT FLAG STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IFS31	IFS30	IFS29	IFS28	IFS27	IFS26	IFS25	IFS24
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IFS23	IFS22	IFS21	IFS20	IFS19	IFS18	IFS17	IFS16
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IFS15	IFS14	IFS13	IFS12	IFS11	IFS10	IFS9	IFS8
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IFS7	IFS6	IFS5	IFS4	IFS3	IFS2	IFS1	IFS0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **IFS31-IFS0:** Interrupt Flag Status bits
1 = Interrupt request has occurred
0 = No interrupt request has occurred

Note: This register represents a generic definition of the IFSx register. Refer to Table 7-1 for the exact bit definitions.

REGISTER 7-5: IECx: INTERRUPT ENABLE CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IEC31	IEC30	IEC29	IEC28	IEC27	IEC26	IEC25	IEC24
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IEC23	IEC22	IEC21	IEC20	IEC19	IEC18	IEC17	IEC16
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IEC15	IEC14	IEC13	IEC12	IEC11	IEC10	IEC9	IEC8
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IEC7	IEC6	IEC5	IEC4	IEC3	IEC2	IEC1	IEC0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **IEC31-IEC0:** Interrupt Enable bits
1 = Interrupt is enabled
0 = Interrupt is disabled

Note: This register represents a generic definition of the IECx register. Refer to Table 7-1 for the exact bit definitions.

REGISTER 8-4: REFOTRIM: REFERENCE OSCILLATOR TRIM REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ROTRIM<8:1>							
23:16	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	ROTRIM<0>	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:	y = Value set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-23 **ROTRIM<8:0>:** Reference Oscillator Trim bits

111111111 = 511/512 divisor added to RODIV value
111111110 = 510/512 divisor added to RODIV value
•
•
•
100000000 = 256/512 divisor added to RODIV value
•
•
•
000000010 = 2/512 divisor added to RODIV value
000000001 = 1/512 divisor added to RODIV value
000000000 = 0/512 divisor added to RODIV value

bit 22-0 **Unimplemented:** Read as '0'

Note: While the ON bit (REFOCON<15>) is '1', writes to this register do not take effect until the DIVSWEN bit is also set to '1'.

REGISTER 9-3: CHETAG: CACHE TAG REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	LTAGBOOT	—	—	—	—	—	—	—
23:16	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	LTAG<19:12>							
15:8	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	LTAG<11:4>							
7:0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-0	R/W-0	R/W-1	U-0
	LTAG<3:0>				LVALID	LLOCK	LTYPE	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **LTAGBOOT:** Line TAG Address Boot bit
- 1 = The line is in the 0x1D000000 (physical) area of memory
- 0 = The line is in the 0x1FC00000 (physical) area of memory

bit 30-24 **Unimplemented:** Write '0'; ignore read

bit 23-4 **LTAG<19:0>:** Line TAG Address bits

LTAG<19:0> bits are compared against physical address to determine a hit. Because its address range and position of PFM in kernel space and user space, the LTAG PFM address is identical for virtual addresses, (system) physical addresses, and PFM physical addresses.

bit 3 **LVALID:** Line Valid bit
- 1 = The line is valid and is compared to the physical address for hit detection
- 0 = The line is not valid and is not compared to the physical address for hit detection

bit 2 **LLOCK:** Line Lock bit
- 1 = The line is locked and will not be replaced
- 0 = The line is not locked and can be replaced

bit 1 **LTYPE:** Line Type bit
- 1 = The line caches instruction words
- 0 = The line caches data words

bit 0 **Unimplemented:** Write '0'; ignore read

REGISTER 11-14: U1FRMH: USB FRAME NUMBER HIGH REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	R-0	R-0	R-0
	—	—	—	—	—	FRMH<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-3 **Unimplemented:** Read as '0'

bit 2-0 **FRMH<2:0>:** The Upper 3 bits of the Frame Numbers bits
The register bits are updated with the current frame number whenever a SOF TOKEN is received.

REGISTER 11-15: U1TOK: USB TOKEN REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	PID<3:0>(1)				EP<3:0>			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-4 **PID<3:0>:** Token Type Indicator bits(1)
0001 = OUT (TX) token type transaction
1001 = IN (RX) token type transaction
1101 = SETUP (TX) token type transaction
Note: All other values are reserved and must not be used.

bit 3-0 **EP<3:0>:** Token Command Endpoint Address bits
The four bit value must specify a valid endpoint.

Note 1: All other values are reserved and must not be used.

12.1 Parallel I/O (PIO) Ports

All port pins have ten registers directly associated with their operation as digital I/O. The data direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx) read the latch. Writes to the latch write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

12.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx, and TRISx registers for data control, some port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the presence of outputs higher than VDD (e.g., 5V) on any desired 5V-tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum VIH specification.

See the **"Device Pin Tables"** section for the available pins and their functionality.

12.1.2 CONFIGURING ANALOG AND DIGITAL PORT PINS

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs must have their corresponding ANSEL and TRIS bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

If the TRIS bit is cleared (output) while the ANSELx bit is set, the digital output level (VOH or VOL) is converted by an analog peripheral, such as the ADC module or Comparator module.

When the PORT register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

12.1.3 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be an NOP.

12.1.4 INPUT CHANGE NOTIFICATION

The input change notification function of the I/O ports allows the PIC32MX330/350/370/430/450/470 devices to generate interrupt requests to the processor in response to a change-of-state on selected input pins. This feature can detect input change-of-states even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a change-of-state.

Five control registers are associated with the CN functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

The CNSTATx register indicates whether a change occurred on the corresponding pin since the last read of the PORTx bit.

Each I/O pin also has a weak pull-up and every I/O pin has a weak pull-down connected to it. The pull-ups act as a current source or sink source connected to the pin, and eliminate the need for external resistors when push-button or keypad devices are connected. The pull-ups and pull-downs are enabled separately using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

Note:	Pull-ups and pull-downs on change notification pins should always be disabled when the port pin is configured as a digital output. They should also be disabled on 5V tolerant pins when the pin voltage can exceed VDD.

An additional control register (CNCONx) is shown in Register 12-3.

12.2 CLR, SET, and INV Registers

Every I/O module register has a corresponding CLR (clear), SET (set) and INV (invert) register designed to provide fast atomic bit manipulations. As the name of the register implies, a value written to a SET, CLR or INV register effectively performs the implied operation, but only on the corresponding base register and only bits specified as '1' are modified. Bits specified as '0' are not modified.

Reading SET, CLR and INV registers returns undefined values. To see the affects of a write operation to a SET, CLR or INV register, the base register must be read.

REGISTER 15-1: WDTCON: WATCHDOG TIMER CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	ON(1,2)	—	—	—	—	—	—	—
7:0	U-0	R-y	R-y	R-y	R-y	R-y	R/W-0	R/W-0
	—	SWDTPS<4:0>					WDTWINEN	WDTCLR

Legend:	y = Values set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Watchdog Timer Enable bit(1,2)
- 1 = Enables the WDT if it is not enabled by the device configuration
- 0 = Disable the WDT if it was enabled in software

bit 14-7 **Unimplemented:** Read as '0'

bit 6-2 **SWDTPS<4:0>:** Shadow Copy of Watchdog Timer Postscaler Value from Device Configuration bits
On reset, these bits are set to the values of the WDTPS <4:0> of Configuration bits.

bit 1 **WDTWINEN:** Watchdog Timer Window Enable bit
- 1 = Enable windowed Watchdog Timer
- 0 = Disable windowed Watchdog Timer

bit 0 **WDTCLR:** Watchdog Timer Reset bit
- 1 = Writing a '1' will clear the WDT
- 0 = Software cannot force this bit to a '0'

Note 1: A read of this bit results in a '1' if the Watchdog Timer is enabled by the device configuration or software.

2: When using the 1:1 PBCLK divisor, the user software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

NOTES:

REGISTER 17-1: OCxCON: OUTPUT COMPARE 'x' CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	ON(1)	—	SIDL	—	—	—	—	—
7:0	U-0	U-0	R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	OC32	OCFLT(2)	OCTSEL	OCM<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Output Compare Peripheral On bit(1)
- 1 = Output Compare peripheral is enabled
- 0 = Output Compare peripheral is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
- 1 = Discontinue operation when CPU enters Idle mode
- 0 = Continue operation in Idle mode

bit 12-6 **Unimplemented:** Read as '0'

bit 5 **OC32:** 32-bit Compare Mode bit
- 1 = OCxR<31:0> and/or OCxRS<31:0> are used for comparisions to the 32-bit timer source
- 0 = OCxR<15:0> and OCxRS<15:0> are used for comparisons to the 16-bit timer source

bit 4 **OCFLT:** PWM Fault Condition Status bit(2)
- 1 = PWM Fault condition has occurred (cleared in HW only)
- 0 = No PWM Fault condition has occurred

bit 3 **OCTSEL:** Output Compare Timer Select bit
- 1 = Timer3 is the clock source for this Output Compare module
- 0 = Timer2 is the clock source for this Output Compare module

bit 2-0 **OCM<2:0>:** Output Compare Mode Select bits
- 111 = PWM mode on OCx; Fault pin is enabled
- 110 = PWM mode on OCx; Fault pin is disabled
- 101 = Initialize OCx pin low; generate continuous output pulses on OCx pin
- 100 = Initialize OCx pin low; generate single output pulse on OCx pin
- 011 = Compare event toggles OCx pin
- 010 = Initialize OCx pin high; compare event forces OCx pin low
- 001 = Initialize OCx pin low; compare event forces OCx pin high
- 000 = Output compare peripheral is disabled but continues to draw current

Note 1: When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: This bit is only used when OCM<2:0> = '111'. It is read as '0' in all other modes.

REGISTER 19-1: I2CxCON: I^{2}C CONTROL REGISTER (CONTINUED)

bit 7 **GCEN:** General Call Enable bit (when operating as I^{2}C slave)
1 = Enable interrupt when a general call address is received in the I2CxRSR (module is enabled for reception)
0 = General call address disabled

bit 6 **STREN:** SCLx Clock Stretch Enable bit (when operating as I^{2}C slave)
Used in conjunction with SCLREL bit.
1 = Enable software or receive clock stretching
0 = Disable software or receive clock stretching

bit 5 **ACKDT:** Acknowledge Data bit (when operating as I^{2}C master, applicable during master receive)
Value that is transmitted when the software initiates an Acknowledge sequence.
1 = Send NACK during Acknowledge
0 = Send ACK during Acknowledge

bit 4 **ACKEN:** Acknowledge Sequence Enable bit
(when operating as I^{2}C master, applicable during master receive)
1 = Initiate Acknowledge sequence on SDAx and SCLx pins and transmit ACKDT data bit. Hardware clear at end of master Acknowledge sequence.
0 = Acknowledge sequence not in progress

bit 3 **RCEN:** Receive Enable bit (when operating as I^{2}C master)
1 = Enables Receive mode for I^{2}C. Hardware clear at end of eighth bit of master receive data byte.
0 = Receive sequence not in progress

bit 2 **PEN:** Stop Condition Enable bit (when operating as I^{2}C master)
1 = Initiate Stop condition on SDAx and SCLx pins. Hardware clear at end of master Stop sequence.
0 = Stop condition not in progress

bit 1 **RSEN:** Repeated Start Condition Enable bit (when operating as I^{2}C master)
1 = Initiate Repeated Start condition on SDAx and SCLx pins. Hardware clear at end of master Repeated Start sequence.
0 = Repeated Start condition not in progress

bit 0 **SEN:** Start Condition Enable bit (when operating as I^{2}C master)
1 = Initiate Start condition on SDAx and SCLx pins. Hardware clear at end of master Start sequence.
0 = Start condition not in progress

Note 1: When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

24.0 COMPARATOR

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 19. "Comparator"** (DS60001110), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

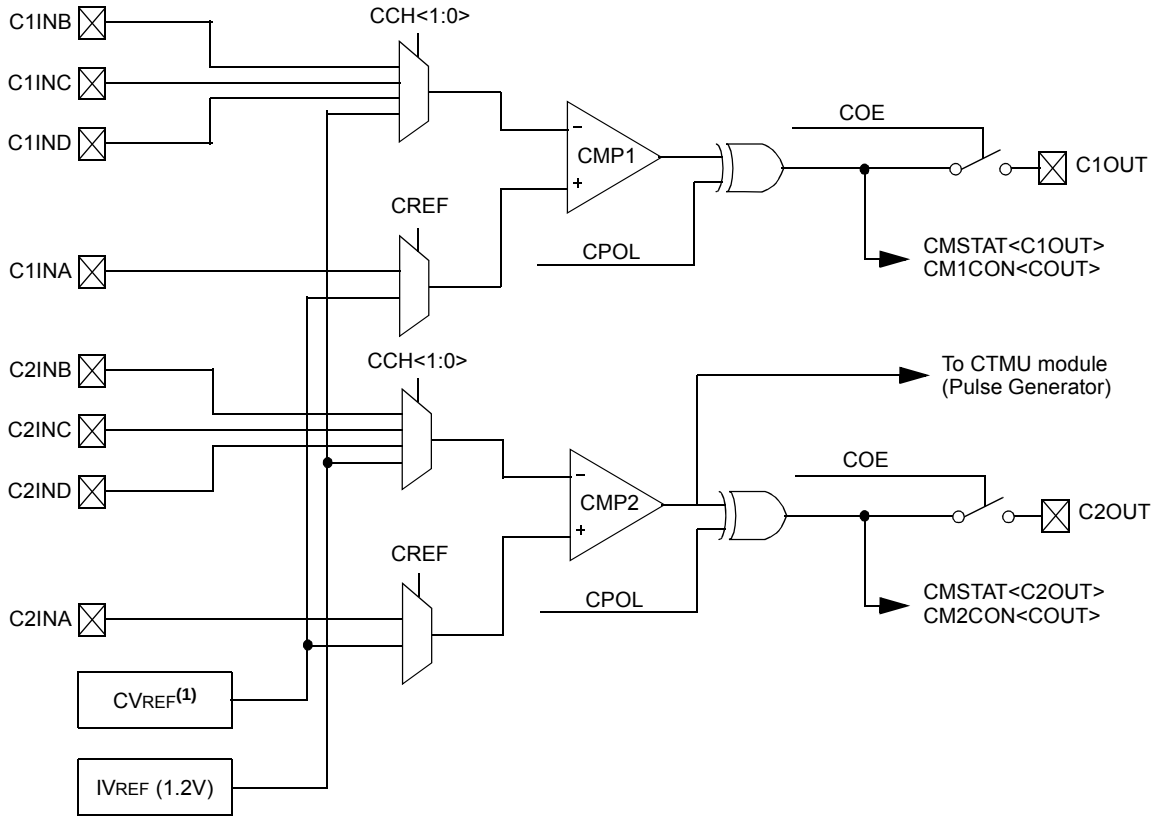
The Analog Comparator module contains two comparators that can be configured in a variety of ways.

The following are key features of this module:

- Selectable inputs available include:
  - Analog inputs multiplexed with I/O pins
  - On-chip internal absolute voltage reference (IVREF)
  - Comparator voltage reference (CVREF)
- Outputs can be Inverted
- Selectable interrupt generation

A block diagram of the comparator module is provided in Figure 24-1.

FIGURE 24-1: COMPARATOR BLOCK DIAGRAM



Note 1: Internally connected. See **Section 25.0 "Comparator Voltage Reference (CVREF)"** for more information.

31.1 DC Characteristics

TABLE 31-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temp. Range (in °C)	Max. Frequency
			PIC32MX330/350/370/430/450/470
DC5	2.3-3.6V(1)	-40°C to +85°C	100 MHz
DC5b	2.3-3.6V(1)	-40°C to +105°C	80 MHz
DC5c	2.3-3.6V(1)	0°C to +70°C	120 MHz

Note 1: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 31-10 for VBORMIN values.

TABLE 31-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typical	Max.	Unit
Commercial Temperature Devices					
Operating Junction Temperature Range	TJ	0	—	+115	°C
Operating Ambient Temperature Range	TA	0	—	+70	°C
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
V-temp Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+105	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – S IOH) I/O Pin Power Dissipation: I/O = S (({VDD – VOH} x IOH) + S (VOL x IOL))	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 31-3: THERMAL PACKAGING CHARACTERISTICS

Characteristics	Symbol	Typical	Max.	Unit	Notes
Package Thermal Resistance, 64-pin QFN (9x9x0.9 mm)	θJA	28	—	°C/W	**1**
Package Thermal Resistance, 64-pin TQFP (10x10x1 mm)	θJA	47	—	°C/W	**1**
Package Thermal Resistance, 100-pin TQFP (12x12x1 mm)	θJA	43	—	°C/W	**1**
Package Thermal Resistance, 100-pin TQFP (14x14x1 mm)	θJA	43	—	°C/W	**1**
Package Thermal Resistance, 124-pin VTLA	θJA	21	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 31-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symb.**	**Characteristics**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
		Input Leakage Current (Note 3)					
DI50	IIL	I/O Ports	—	—	±1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		Analog Input Pins	—	—	±1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI55		$\overline{MCLR}$(2)	—	—	±1	μA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	—	—	±1	μA	VSS ≤ VPIN ≤ VDD, XT and HS modes
DI60a	IICL	**Input Low Injection Current**	0	—	-5(7,10)	mA	Pins with Analog functions. Exceptions: [N/A] = 0 mA max
							Digital 5V tolerant designated pins. Exceptions: [N/A] = 0 mA max
							Digital non-5V tolerant designated pins. Exceptions: [N/A] = 0 mA max

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

5: See the **"Device Pin Tables"** section for the 5V tolerant pins.

6: The VIH specifications are only in relation to externally applied inputs, and not with respect to the user-selectable internal pull-ups. External open drain input signals utilizing the internal pull-ups of the PIC32 device are guaranteed to be recognized only as a logic "high" internally to the PIC32 device, provided that the external load does not exceed the minimum value of ICNPU. For External "input" logic inputs that require a pull-up source, to guarantee the minimum VIH of those components, it is recommended to use an external pull-up resistor rather than the internal pull-ups of the PIC32 device.

7: VIL source < (VSS - 0.3). Characterized but not tested.

8: VIH source > (VDD + 0.3) for non-5V tolerant pins only.

9: Digital 5V tolerant pins do not have an internal high side diode to VDD, and therefore, cannot tolerate any "positive" input injection current.

10: Injection currents > | 0 | can affect the ADC results by approximately 4 to 6 counts (i.e., VIH Source > (VDD + 0.3) or VIL source < (VSS - 0.3)).

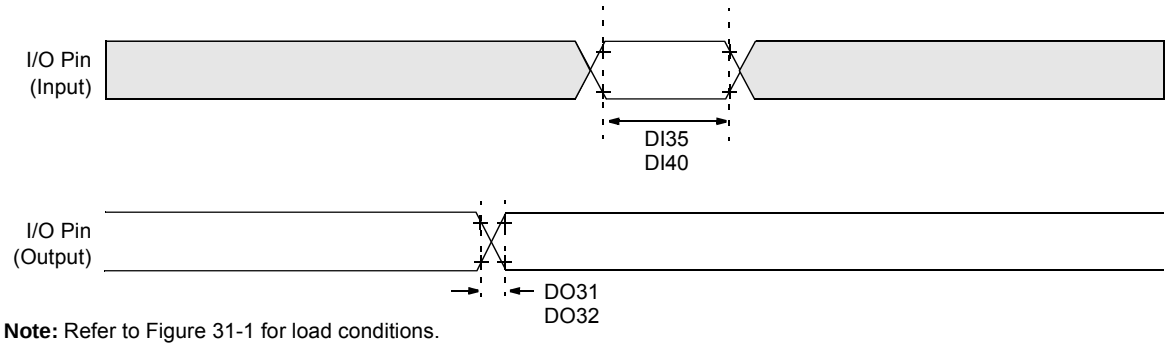
11: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. If **Note 7**, IICL = (((Vss - 0.3) - VIL source) / Rs). If **Note 8**, IICH = ((IICH source - (VDD + 0.3)) / RS). RS = Resistance between input source voltage and device pin. If (VSS - 0.3) ≤ VSOURCE ≤ (VDD + 0.3), injection current = 0.

TABLE 31-21: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
LPRC @ 31.25 kHz(1)						
F21	LPRC	-15	—	+15	%	—

Note 1: Change of LPRC frequency as VDD changes.

FIGURE 31-3: I/O TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

TABLE 31-22: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(2)**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	5	15	ns	VDD < 2.5V
			—	5	10	ns	VDD > 2.5V
DO32	TIOF	Port Output Fall Time	—	5	15	ns	VDD < 2.5V
			—	5	10	ns	VDD > 2.5V
DI35	TINP	INTx Pin High or Low Time	10	—	—	ns	—
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TSYSCLK	—

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

2: This parameter is characterized, but not tested in manufacturing.

TABLE 31-33: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

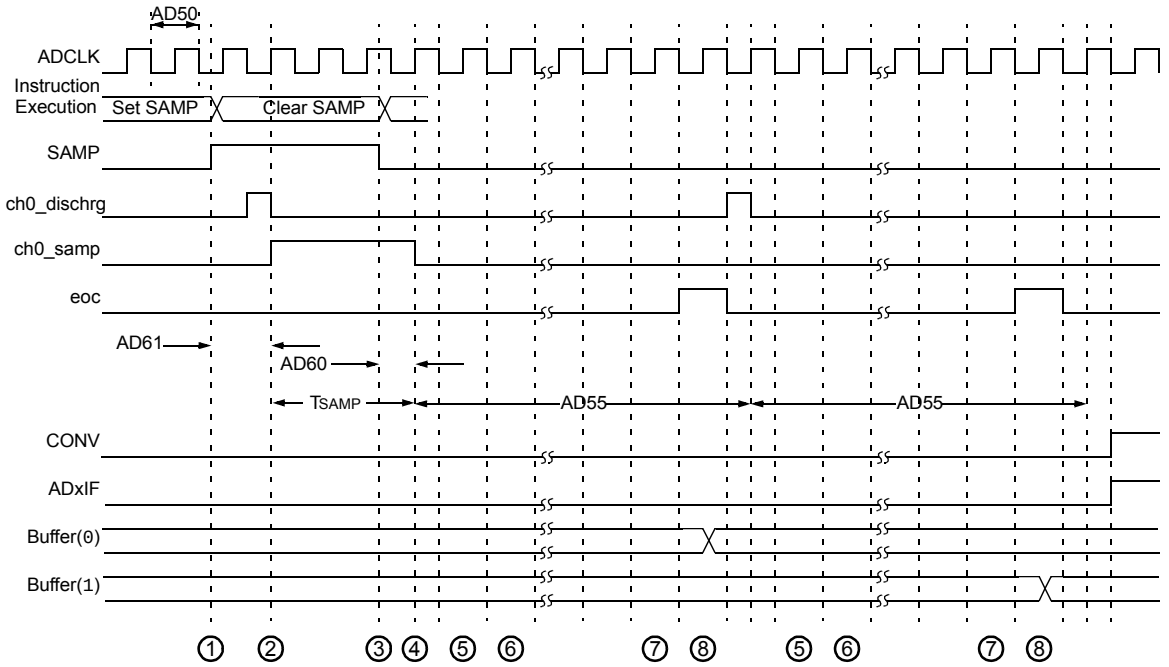
AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 2)**	100	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode **(Note 2)**	0	0.3	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	

Note 1: BRG is the value of the I^2C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: The typical value for this parameter is 104 ns.

FIGURE 31-18: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 0, SSRC<2:0> = 000)



(1) – Software sets ADxCON. SAMP to start sampling.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104) in the *"PIC32 Family Reference Manual"*.

(3) – Software clears ADxCON. SAMP to start conversion.

(4) – Sampling ends, conversion sequence starts.

(5) – Convert bit 9.

(6) – Convert bit 8.

(7) – Convert bit 0.

(8) – One TAD for end of conversion.

APPENDIX A: REVISION HISTORY

Revision A (July 2012)

This is the initial released version of the document.

Revision B (April 2013)

Note: The status of this data sheet was updated to Preliminary; however, any electrical specifications listed for PIC32MX370/470 devices is to be considered Advance Information and is marked accordingly.

This revision includes the following updates, as shown in Table A-1.

TABLE A-1: MAJOR SECTION UPDATES

Section	Update Description
"32-bit Microcontrollers (up to 512 KB Flash and 128 KB SRAM) with Audio/Graphics/Touch (HMI), USB, and Advanced Analog"	SRAM was changed from 32 KB to 64 KB. Data Memory (KB) was changed from 32 to 64 for the following devices (see Table 1): • PIC32MX350F256H • PIC32MX350F256L • PIC32MX450F256H • PIC32MX450F256L The following devices were added: • PIC32MX370F512H • PIC32MX370F512L • PIC32MX470F512H • PIC32MX470F512L
4.0 "Memory Organization"	The Memory Map for Devices with 256 KB of Program Memory was updated (see Figure 4-3). The Memory Map for Devices with 512 KB of Program Memory was added (see Figure 4-4).
7.0 "Interrupt Controller"	Updated the Interrupt IRQ, Vector and Bit Locations (see Table 7-1).
20.0 "Parallel Master Port (PMP)"	Added the CS2 bit and updated the ADDR bits in the Parallel Port Address register (see Register 20-3).
27.0 "Special Features"	Updated the PWP bit in the Device Configuration Word 3 register (see Register 27-4).
30.0 "Electrical Characteristics"	Note 2 in the DC Characteristics: Operating Current (I_{DD}) were updated (see Table 30-5). Note 1 in the DC Characteristics: Idle Current (I_{IDLE}) were updated (see Table 30-6). Note 1 in the DC Characteristics: Power-down Current (I_{PD}) were updated (see Table 30-7). Updated Program Memory values for parameters D135 (T_{WW}), D136 (T_{RW}), and D137 (T_{PE} and T_{CE}) (see Table 30-12).
31.0 "DC and AC Device Characteristics Graphs"	New I_{DD}, I_{IDLE}, and I_{PD} current graphs were added for PIC32MX330/430 devices and PIC32MX350/450 devices.